

MECHANICAL CASE OUTLINE

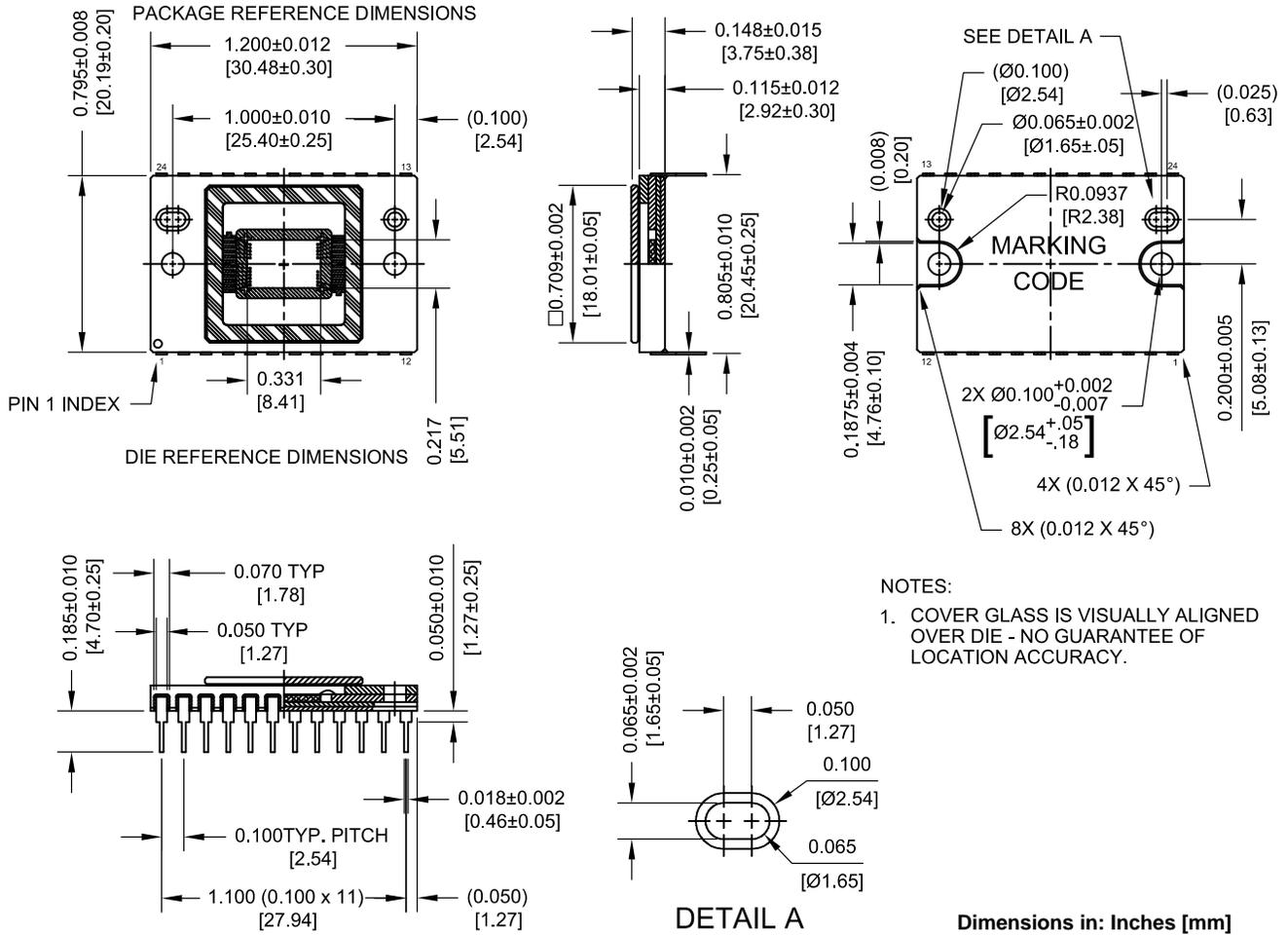
PACKAGE DIMENSIONS

ON Semiconductor®



CERAMIC DIP 24, 30.48x20.19 CASE 125AY ISSUE O

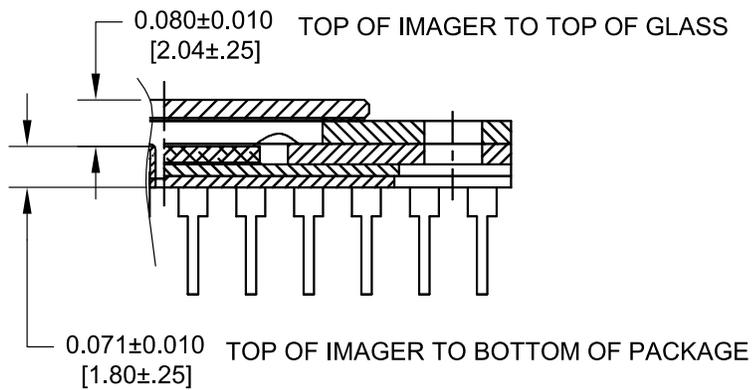
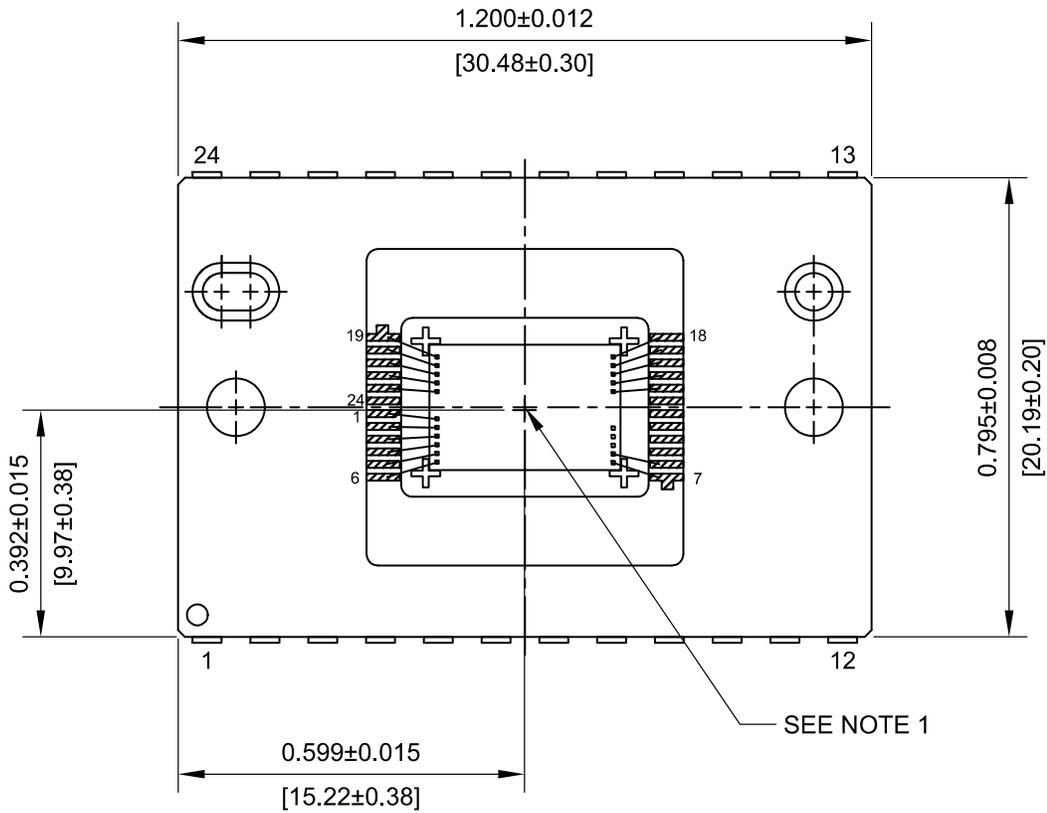
DATE 30 JUL 2014



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NOTES:

1. CENTER OF IMAGE AREA IS OFFSET FROM CENTER OF PACKAGE BY (-0.02,-0.13)mm NOMINAL.
2. DIE IS VISUALLY ALIGNED WITHIN ± 2° OF ANY PACKAGE CAVITY EDGE.

Dimensions in: Inches [mm]

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